INFORMATION DISCLOSURE CITATION PTO-1449	ATTY. DOCKET NO. P19-US	SERIAL NO. 10/005,308
	APPLICANT Satayadev R. Patel, et al.	
	FILING DATE 12/03/01	GROUP 2812

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet 1 of 3

Complet if Known	
Application Number	10/005,308
Filing Date	December 3, 2001
First Named Inventor	PATEL et al.
Art Unit	2812
Examiner Name	
Attorney Docket Number	P19-US

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Examiner Signature		Date Considered	5/4/04

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Sheet 2 of 2

Complete if Known	
Application Number	10/005,308
Filing Date	December 3, 2001
First Named Inventor	PATEL et al.
Group Art Unit	2812
Examiner Name	
Attorney Docket Number	P19-US

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	APPLICANT Satayadev R. Patel, et al.	
	FILING DATE 12/03/01	GROUP 2812

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EXAMINER Matthew C. Luu	DATE CONSIDERED 5/4/04

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	APPLICANT Satayadev R. Patel, et al.	
	FILING DATE 12/03/01	GROUP 2812

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